

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5549105

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KEAN HUAT LEONG	08/09/2018
CHUN KIT SEE	08/09/2018
SHENG JIAN DARREN TAN	08/09/2018
PAIK WEN ONG	08/09/2018
ENG HUAT GOH	08/09/2018
RECEIVING PARTY DATA	
Name:	INTEL CORPORATION
Street Address:	2200 MISSION COLLEGE BLVD.
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16018940
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	612-373-6900
Email:	request@slwip.com
Correspondent Name:	SCHWEGMAN, LUNDBERG & WOESSNER/INTEL
Address Line 1:	PO BOX 2938
Address Line 4:	MINNEAPOLIS, MINNESOTA 55402
ATTORNEY DOCKET NUMBER:	1884.115US1
NAME OF SUBMITTER:	NANCY CUNDALL
SIGNATURE:	/Nancy Cundall/
DATE SIGNED:	05/31/2019
Total Attachments: 3	
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RECORDATION FORM COVER SHEET
PATENTS ONLY

Atty Ref/Docket No.: (P114101MY-US) 1884.115US1

Patent and Trademark Office

To the Director of the U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Kean Huat Leong, Chun Kit See, Sheng Jian Darren Tan,
Paik Wen Ong, Eng Huat Goh

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: August 9, 2018, August 9, 2018, August
9, 2018, August 9, 2018, August 9, 2018

2. Name and address of receiving party(ies):

Name: Intel Corporation

Street Address: 2200 Mission College Blvd.

City: Santa Clara State: CA Zip: 95054

Country: United States of America

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

B. Patent No.(s)

Serial No. 16/018,940

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence
concerning document should be mailed:

Name: John N. Greaves

Address:

Schwegman Lundberg & Woessner, P.A.
P.O. Box 2938
Minneapolis, Minnesota 55402

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 0.00

☐ Enclosed

☐ Authorized to be charged to deposit account
190743

8. Please charge any additional fees or credit any over
payments to our Deposit Account No.: 190743

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of
the original document.



John N. Greaves/Reg. No. 40,362

Name of Person Signing

Signature

30. May 2019

Date

Total number of pages including cover sheet: 3

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks
Mail Stop Assignment Recordation Services
P.O. Box 1450
Alexandria, VA 22313-1450

PATENT
REEL: 049328 FRAME: 0223

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

<Kean Huat Leong, Chun Kit See, Sheng Jian Darren Tan, Paik Wen Ong, Eng Huat Goh>

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

SEMICONDUCTOR PACKAGE SUBSTRATE SUPPORT STRUCTURES FOR BALL-GRID ARRAY CAVITIES, AND METHODS OF ASSEMBLING SAME

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on June 26, 2018 as

United States of America Application Number 16/018,940

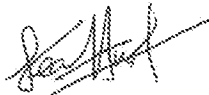
which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute

all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



Kean Huat Leong

9 AUG 2018

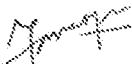
Date Signed



Chun Kit See

9 AUG 2018

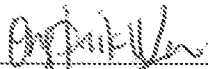
Date Signed



Sheng Jian Darren Tan

9 AUG 2018

Date Signed



Paili Wen Ong

9 AUG 2018

Date Signed



Eng Huat Goh

9 AUG 2018

Date Signed